

**BC860**  
Rev.F Apr.-2017

JF K\$) \*      GE G`      Silicon PNP transistor in a SOT-23 Plastic Package.

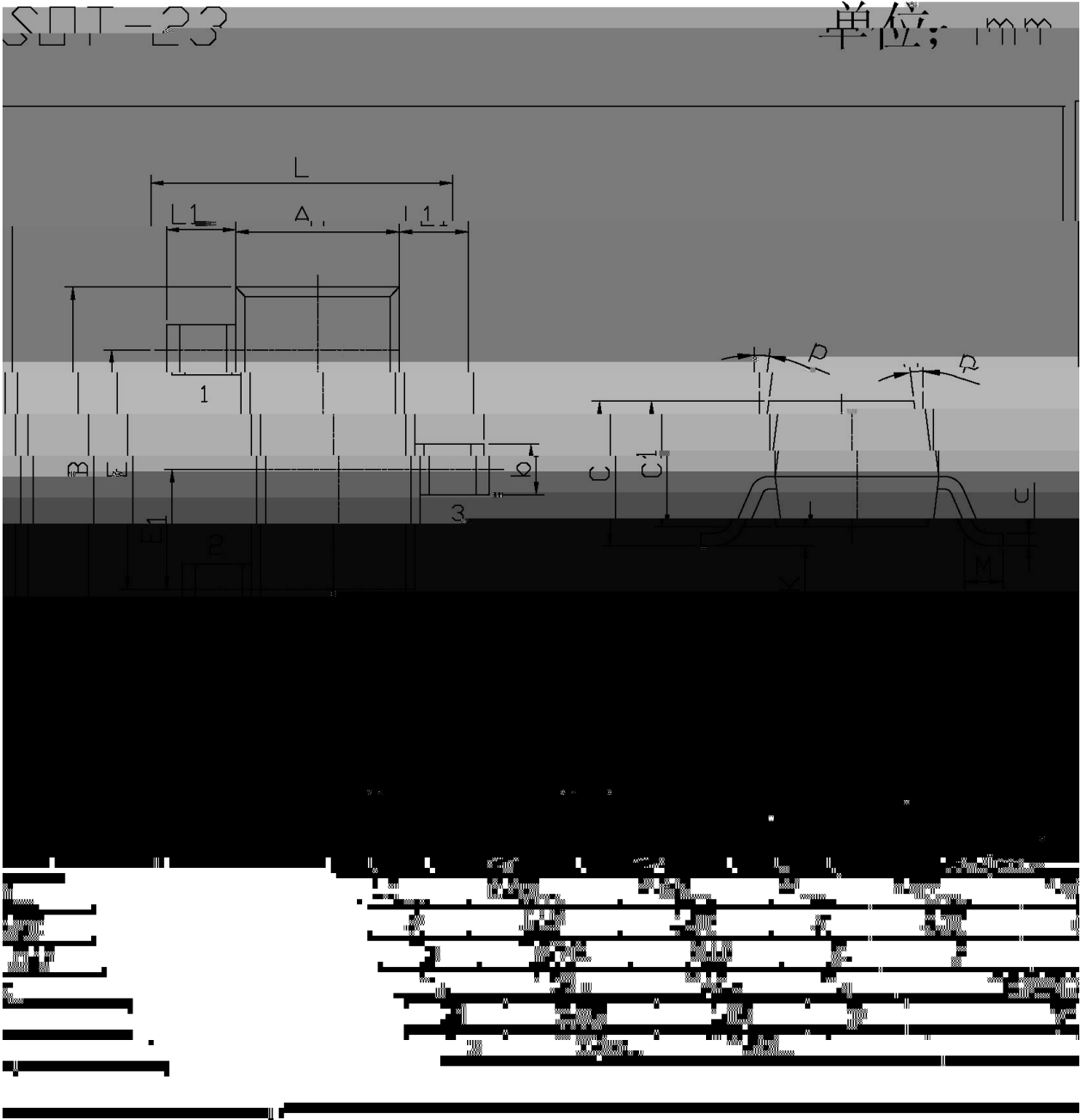
$V_{CE(sat)}$   
High current gain, Low collector-emitter saturation voltage.

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	-50	V
Collector to Emitter Voltage	$V_{CEO}$	-45	V
Emitter to Base Voltage	$V_{EBO}$	-5.0	V
Collector Current - Continuous	$I_C$	-100	mA
Collector Power Dissipation	$P_C$	350	mW
Junction Temperature	$T_j$	150	
Storage Temperature Range	$T_{stg}$	-55 150	

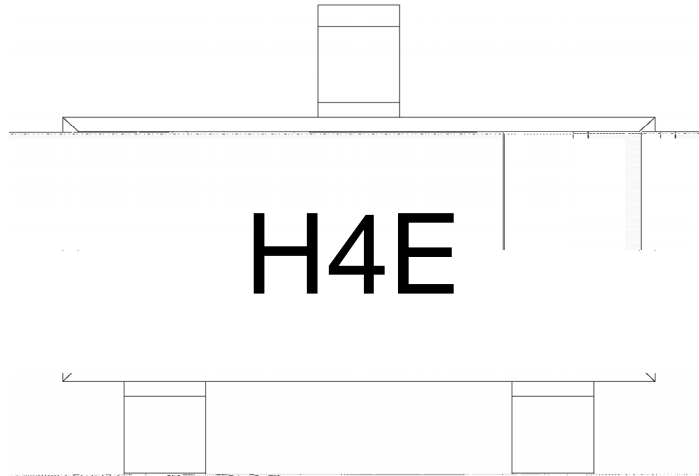
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown Voltage	$V_{CEO}$	$I_C = -10mA$ $I_B = 0$	-45			V
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C$ I E O				



/ Package Dimensions

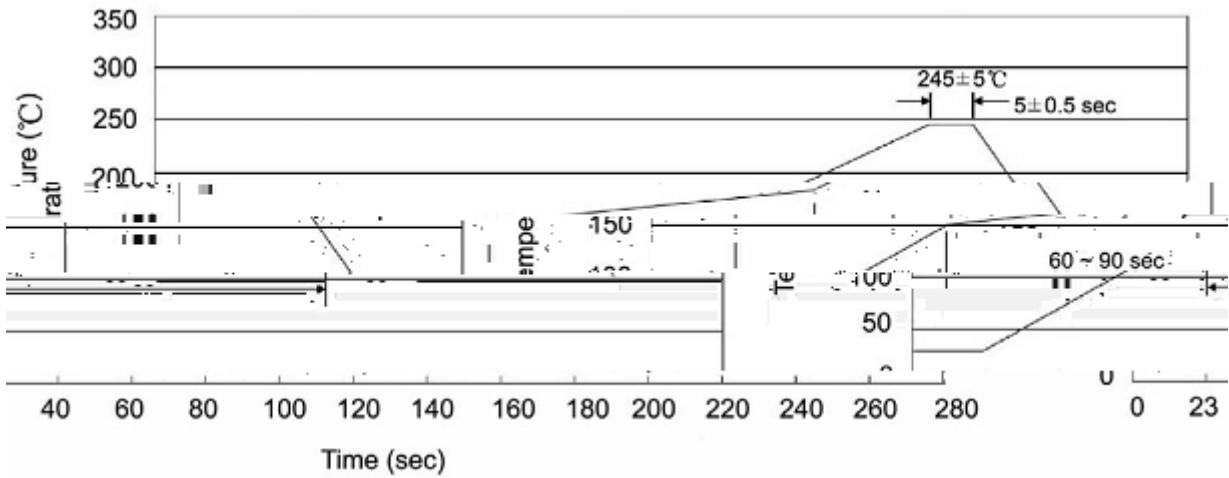


**/ Marking Instructions**



- ? . . . . .
- +< . . . . .
- Note:**
- H:       Company Code.
- 4E:      Product Type Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |        |     |            |          |   |
|---|--------|-----|------------|----------|---|
| 1 | 25     | 150 | 60         | 90sec;   | 1.Preheating:25~150 , Time:60~90sec.      |
| 2 | 245..5 |     | 5..0.5sec; |          | 2.Peak Temp.:245..5 , Duration:5..0.5sec. |
| 3 |        |     | 2          | 10 /sec. | 3. Cooling Speed: 2~10 /sec.              |

/ Resistance to Soldering Heat Test Conditions

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm <sup>3</sup> )		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices